

Innovative Final Finish – Autocatalytic Silver Immersion Gold

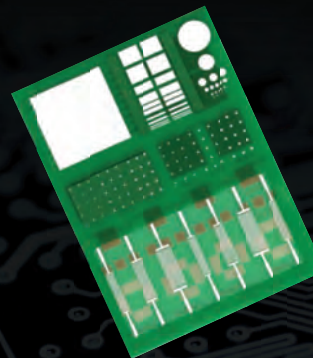
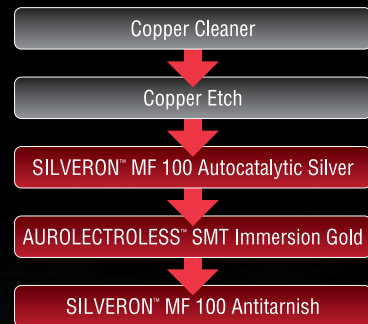
新式表面处理技术-化学银置换金

SILVERON™ MF 100 Electroless Silver/ AUROLECTROLESS™ SMT Immersion Gold

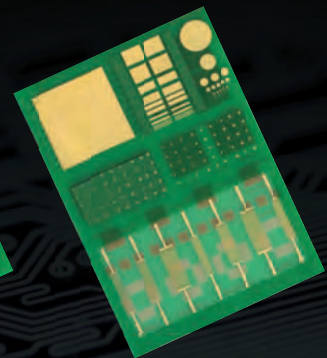
Features and Benefits 特性及优点

- Silver plus anti-tarnish has the performance capability of ENIG, without nickel issues (corrosion and ground plating)
本製程不含Ni，所以组装时无黑镍与细线路短接风险，但同时具备化学镍金相当的能力
- Strong solder joints: solder bonds to copper rather than nickel, no brittle intermetallics
焊点可靠度高：錫锡直接与铜熔接，不会形成脆性合金层
- The autocatalytic nature produces high density silver layer to prevent diffusion of copper to the silver surface and reduce oxide formation
自我催化沉积银层的密度高，预防铜迁移到银表面，同时也降低了氧化风险
- Multiple reflow capabilities with excellent solderability
可耐多次迴焊仍有优异的焊接能力
- Excellent wire bonding capability
在打铝线与打金线具有优异的信賴度表现
- Superior “RF” performance compared to nickel due to conductivity of silver
银比化学镍导体更优异的无线电传输性能

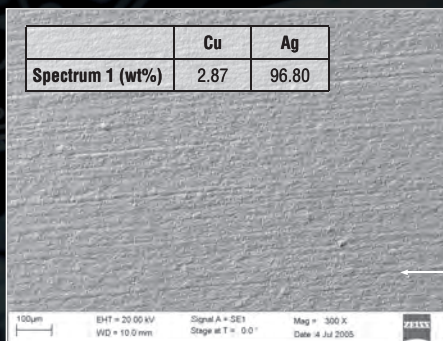
Process 流程



AS + Anti-tarnish finish



ASIG finished



Silver surface after 8 hours ageing in 155°C with extremely low copper content on the surface



Dense silver grain structure



Electronic Materials